



SONICS[®]
SONICS & MATERIALS, INC.

OEM COMPONENTS

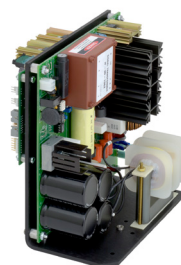
- Economical and space-saving ultrasonics
- Maximum flexibility
- Sequentially switch RF signal from 1 kit to several locations
- Strong weld without marking Class A surface or visible part side
- Kits for NEMA enclosures and PLC sequencing



F-Series Generator Kits for 20 & 40 kHz frequencies (800, 1200, 1700 & 2200 watts power)

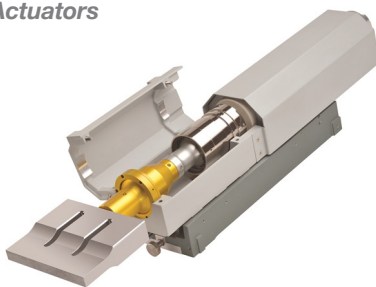
ultrasonic OEM kits and components

for seamless integration into special assembly systems



H-Series Generator Kits for 20 & 40 kHz frequencies (500 watts power)

Self-contained Pneumatic Actuators



Converter, Booster and Horn Stacks



CUSTOM TOOLING & FIXTURES:

- Designed with FEA simulation program
- Segmented and adjustable fixtures for secure fit with molded plastic parts
- Contoured fixtures and tools for irregularly shaped parts
- Carbide facing or chrome plating applied for strength and durability
- Soft peripheral devices to clamp, hold and align opposing parts also available



Multi-Channel High Voltage Switching Sequencer for up to 8 ultrasonic converter stacks

Leaders in the field of ultrasonic plastics welding equipment and technology since 1969, Sonics & Materials offers an array of OEM kits and stack components designed for installation into special assembly systems. Our OEM applications specialists can be contacted directly online or at the number below.

for more information: **1-800-745-1105** www.sonics.com

Innovating
since

1969

stack sequencer overview

Available in 4, 8 and 16 relay channel platforms and compatible with either 40 kHz or 20 kHz frequency components, the function of the Sequencer is to provide a reliable method of sequentially switching a single ultrasonic generator between as many as 16 independent ultrasonic converter stacks.



sequencer models HVM-4 and HVM-8 (with optional mounting plate)

sequencer note

To prevent arcing, two internal delay times of 250 milliseconds each are provided to briefly delay the time between the switching of the relays. The first delay is “Ring Down” time which allows energy within the ultrasonic converter to dissipate and the second delay is “Relay Bounce” time which allows the relay to settle before releasing contact for the next sequential converter stack command for ultrasonics on.

